



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Seigi AOYAMA et al.

Application S/N 09/892,630

Filed: June 28, 2001

: Art Unit: 2827

: Examiner: T. Dinh

For: LEAD-FREE SOLDER, AND CONNECTION LEAD AND ELECTRICAL
COMPONENT USING SAID LEAD-FREE SOLDER

AMENDMENT

Honorable Assistant Commissioner
for Patents
Washington, DC 20231

Sir:

In response to the Official Action dated May 9, 2002, the time for response to which is extended one (1) month up to and including September 9, 2002, please amend the above referenced application as follows.

IN THE FIGURES

Please amend Figures 6, 7A and 7B as indicated on the sheets submitted herewith under a Request for Approval of Drawing Changes. Also attached to the Request are separate sheets showing Figures 6, 7A and 7B with the modifications indicated in red.

9/a
9/10/02
JWR.

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